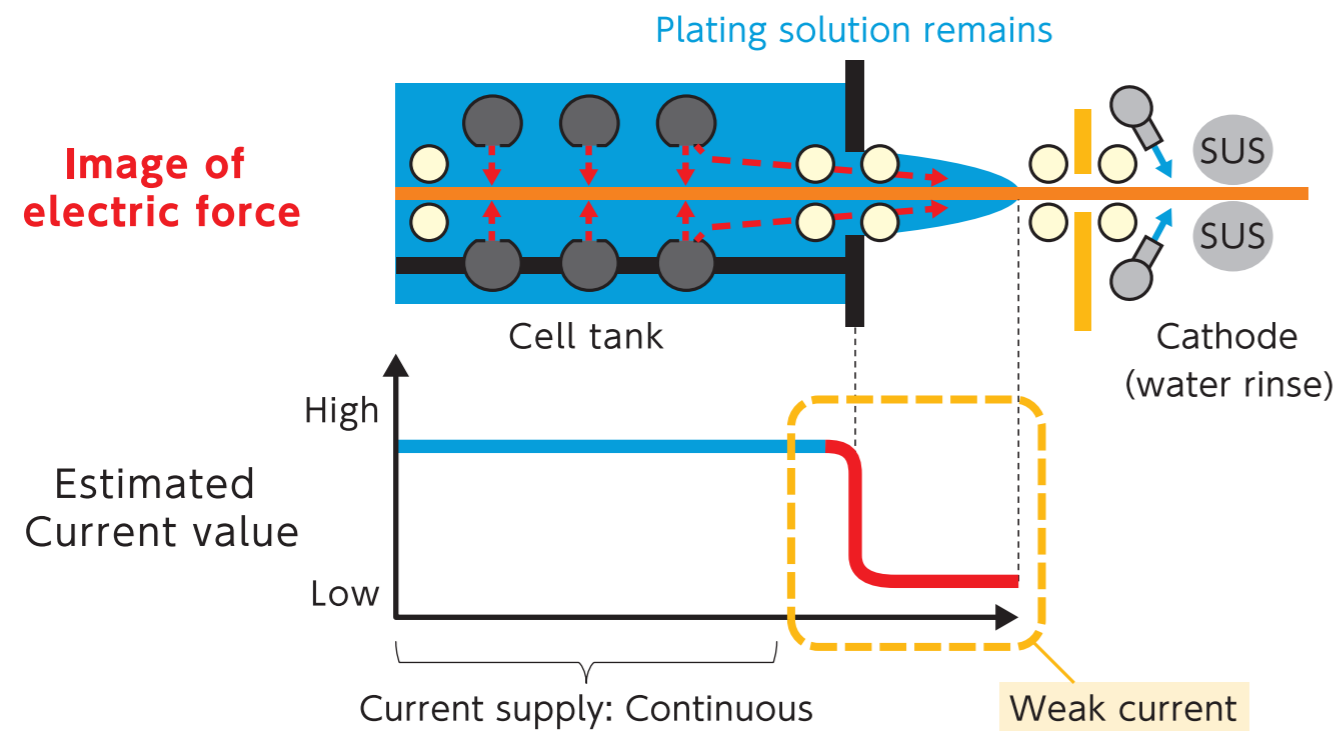


# TOP LUCINA SVP

## Additives for acid copper plating to roll to roll plating

- Realize via-filling plating by horizontal plating equipment
- Reduce the impact by weak current
- Great via-filling and throwing power performance (Patented)



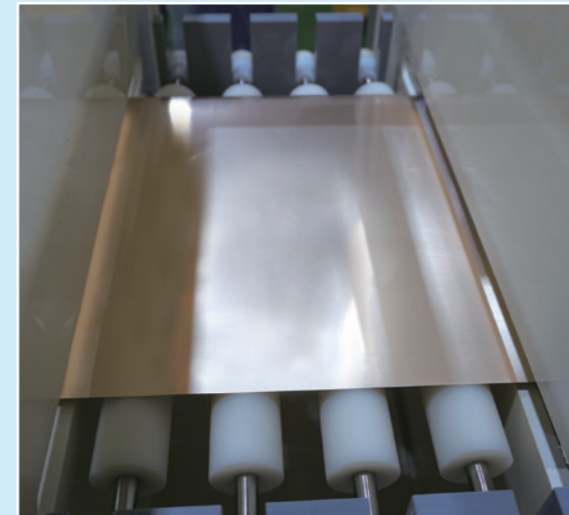
### Realize full filling for horizontal Roll to Roll equipment

	TOP LUCINA SVP	Conventional
Filling performance Via diameter 75μm Via depth 36μm		
Throwing power Diameter 100μm	135%	118%

Plating condition (6A/dm<sup>2</sup>, 30s)⇔(0.2A/dm<sup>2</sup>, 5s) Surface thickness 12μm

**New equipment:  
Horizontal Roll to Roll plating equipment  
in our factory (Osaka)**

**Can treat Flexible Copper Clad Laminates  
With 250mm width**



**By prototype test in our pilot line,  
we find the best chemicals  
and processes especially for you.**

